

REMOVAL OF MEMORY CHIPS

STEP 1. APPLY A LIBERAL AMOUNT OF FLUX TO THE AREA SURROUNDING THE MEMORY CHIP. PLACE 200 WATT HEXAGON SOLDER IRON ON THE DESIRED MEMORY CHIP IN THE MANNER SHOWN IN FIGURE M-1. PRESS DOWN GENTLY WHILE WAITING FOR THE SOLDER TO FLOW. ONCE THE SOLDER FLOWS ENOUGH TO ALLOW THE CHIP TO MOVE, REMOVE THE IRON AND, WITH A TWEEZERS, REMOVE THE CHIP.

STEP 2. USING THE SOLDER WICK MATERIAL, REMOVE THE EXCESS SOLDER FROM THE LEGLESS CONNECTOR BOARD PADS. REFER TO FIGURE M-2.

STEP 3. REMOVE FLUX RESIDUE FROM THE AREA. ALSO, REMOVE ANY RESIDUAL SUPER-GLUE LEFT IN THE CENTER OF THE BOARD PAD AREA. THESE CONDITIONS ARE ABSOLUTELY ESSENTIAL TO THE MAINTENANCE OF THE .015 IN. CHIP-TO-LAYER 6 TOLERANCE BETWEEN STACKED BOARDS ON A MODULE.

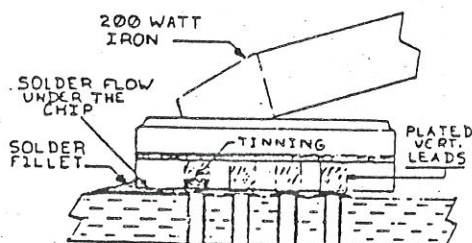


FIG. M-1

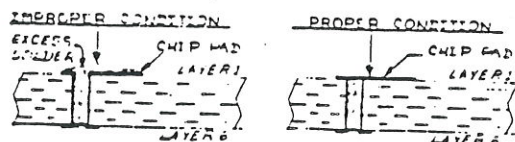
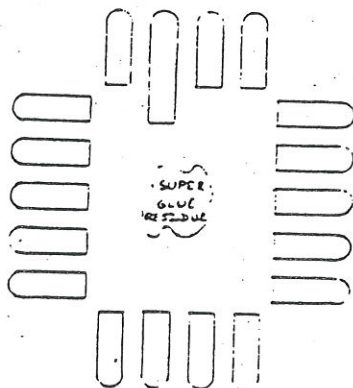


FIG. M-2